Tool ID: 308
Tool Location: 107

Equipment Information Sheet

OEM Endeavor M1

Manager: Tom Pennell 607-254-4309 Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- No unusual hazards during operation.

USAGE RESTRICTIONS

- No buddy system required.

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 30 minutes

- Maximum 4 hr block reservations anytime - Must leave a 4hr block between reservations
- Maximum 12 hours reserved in advance at any time.

No photoresist allowed in this tool.

Specific metal and dielectric layers allowed. Please consult staff for guidance.

MATERIALS COMPATIBILITY CATEGORY

Tool Category 2: Silicon Based Substrates and Select Refractory Metals

Allowed	Not Allowed
Tool category 1/1E materials	No Glass Substrates
Silicon Based Materials only	No CNF Class A or Class B metals and oxides/compounds of (exposed or buried) (ie Magnesium, Zinc, Barium, Calcium)
Si, SiC, SiO_2 substrates	
All Furnace grown or deposited films	
PECVD Films	No Gold, Silver or Copper (Exposed or buried)
ALD dieletric films	No High Vapor pressure materials
CNF Refractory Metals (ie Al, Ti,Ta,W,Pt,Mo,Cr,Ni)	No III/V Compound Semiconductors
Nitrides and Oxides of above metals	No Organic/Biology Molecules prepared-with or without Salt buffers
Cured organics and baked Photoresist	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- CMOS compatible metals only at this time.
- - Adhesives are not allowed (scotch tape, Kapton tape, glues, epoxies, greases, etc are not allowed) in the chamber. Only use clips to secure substrates.
- Photoresist is not allowed in this tool due to the high temperatures of the deposition process.

Last Updated: 04/15/2026